

Process Change Notice

Parts Affected:

Small signal discrete semiconductors, wafers, and die in chip form.

Extent of Change:

Reduction in the standard die thickness of discrete, small signal wafers from 9.0 mils (230 μ m) \pm 0.6 mils (15 μ m), to 7.1 mils (180 μ m) \pm 0.8 mils (20 μ m).

Reason for Change:

To accommodate assemblies of surface mount, epoxy molded packages, with very low package height (<1.0mm).

Effect of Change:

This change does not affect the electrical characteristics of any device.

Effective Date of Change:

Existing inventory will be shipped until depleted.

Sample Availability:

Please contact Salesperson or Manufacturer's Representative.

Chip Process Part Numbers Affected

| <u>Standard Wafer Process Number</u> <u>9.0 mils thickness (230µm)</u> | <u>New Wafer Process Number</u> <u>7.1 mils thickness (180µm)</u> |
|---|--|
| CPD48 | CPD48V |
| CPD76 | CPD76V |
| CPD78 | CPD78V |
| CPD80 | CPD80V |
| CPD83 | CPD83V |
| CPD88 | CPD88V |
| CPD91 | CPD91V |
| CPD92 | CPD92V |
| CPD96 | CPD96V |
| CP188 | CP188V |
| CP191 | CP191V |
| CP192 | CP192V |
| CP305 | CP305V |
| CP307 | CP307V |
| CP309 | CP309V |
| CP310 | CP310V |
| CP314 | CP314V |
| CP315 | CP315V |
| CP316 | CP316V |
| CP317 | CP317V |
| CP318 | CP318V |
| CP324 | CP324V |
| CP355 | CP355V |
| CP392 | CP392V |
| CP588 | CP588V |
| CP591 | CP591V |
| CP592 | CP592V |
| CP705 | CP705V |
| CP709 | CP709V |
| CP710 | CP710V |
| CP716 | CP716V |
| CP720 | CP720V |
| CP734 | CP734V |
| CP755 | CP755V |
| CP767 | CP767V |
| CP792 | CP792V |